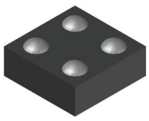
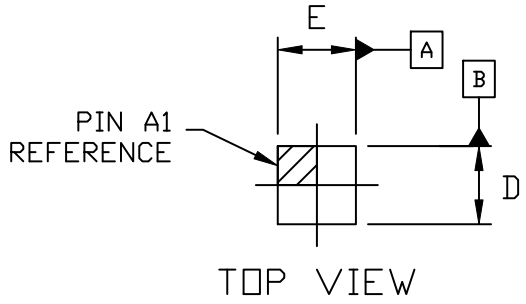
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

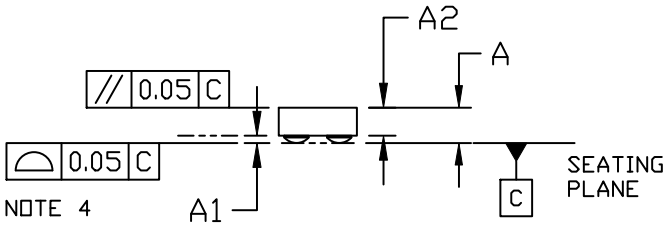


WLCSP4, 0.64x0.64x0.33
CASE 567JZ
ISSUE B

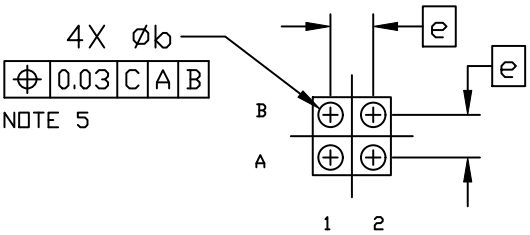
DATE 16 MAY 2022



TOP VIEW



SIDE VIEW

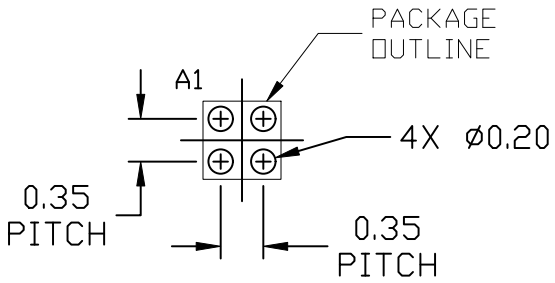


BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE SOLDER BUMPS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	---	---	0.33
A1	0.04	0.06	0.08
A2	0.23 REF		
b	0.180	0.200	0.220
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.35 BSC		



RECOMMENDED
MOUNTING FOOTPRINT *
(NSMD PAD TYPE)

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*

X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP4, 0.64X0.64x0.33**	**PAGE 1 OF 1**

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